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Dr. Edelstein is an IBM Fellow, and Chief Interconnect Strategist in IBM’s Semiconductor Technology Research and Development organization. He has worked for over 35 years on nearly all aspects of Cu- and Cu/Low-k ULSI multilevel on-chip interconnect (BEOL) and related technologies, for high-performance microelectronics products. He currently holds 310 U.S. patents, and has received and shared various high-level awards, including several IBM Corporate, 2004 National Medal of Technology, “Inventor of the Year 2006” by NYSIPLA, 2006 IBM Fellow, 2011 election to the U.S. NAE, and 2019 IEEE Cledo Brunetti Award.